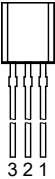



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	 TO-92 (SOT54)	 sym037
2	G	gate		
3	K	cathode		

6. Ordering information

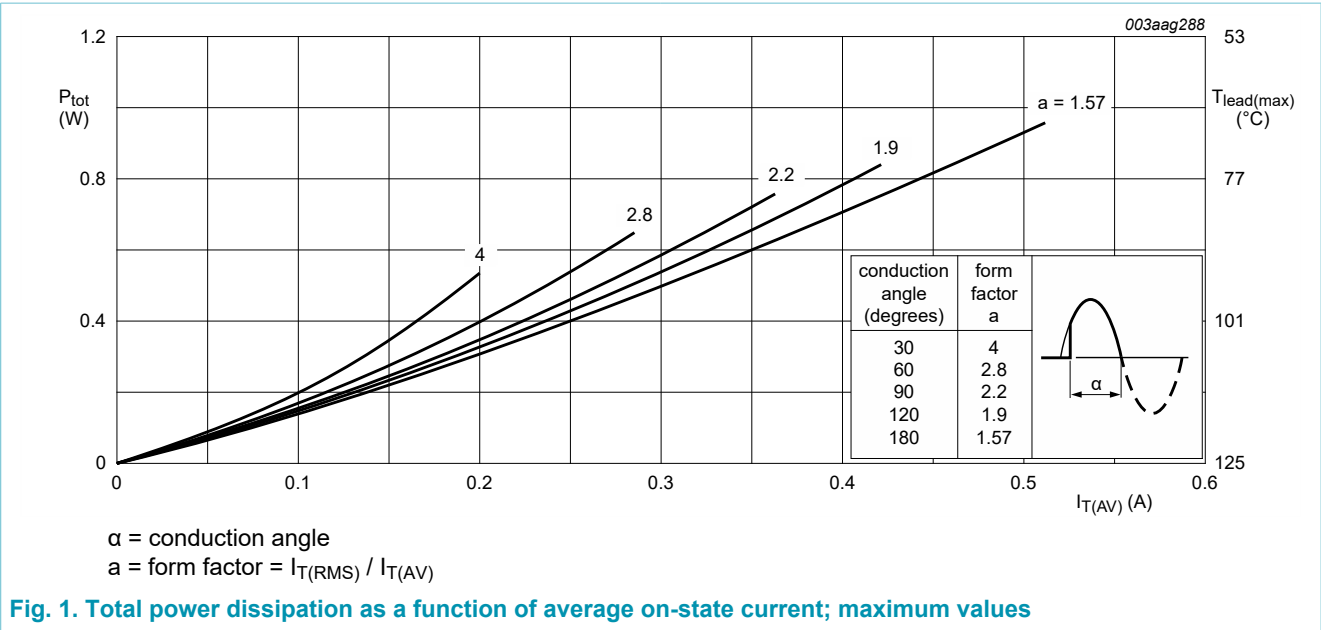
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
N0118GA	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54

7. Limiting values

Table 4. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	600	V
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{lead} \leq 67\text{ }^{\circ}\text{C}$ ; Fig. 1	-	0.51	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{lead} \leq 67\text{ }^{\circ}\text{C}$ ; Fig. 2; Fig. 3	-	0.8	A
$I_{TSM}$	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 10\text{ ms}$ ; Fig. 4; Fig. 5	-	8	A
		half sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 8.3\text{ ms}$	-	9	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; SIN	-	0.32	$\text{A}^2\text{s}$
$dl_T/dt$	rate of rise of on-state current	$I_T = 0.8\text{ A}$ ; $I_G = 10\text{ mA}$ ; $dI_G/dt = 0.1\text{ A}/\mu\text{s}$	-	50	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current		-	1	A
$V_{RGM}$	peak reverse gate voltage		-	5	V
$P_{GM}$	peak gate power		-	2	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.1	W
$T_{stg}$	storage temperature		-40	150	$^{\circ}\text{C}$
$T_j$	junction temperature		-	125	$^{\circ}\text{C}$



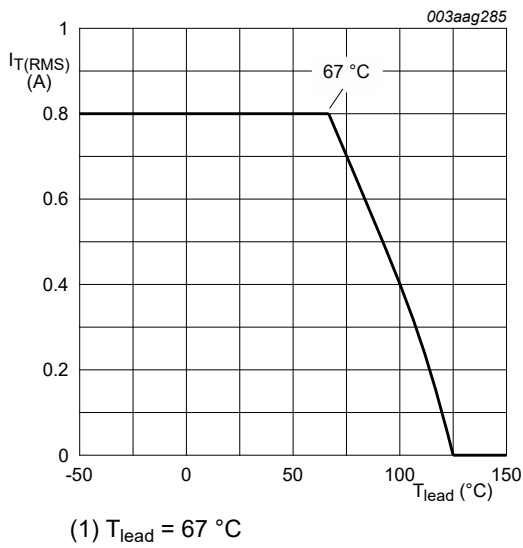


Fig. 2. RMS on-state current as a function of lead temperature; maximum values

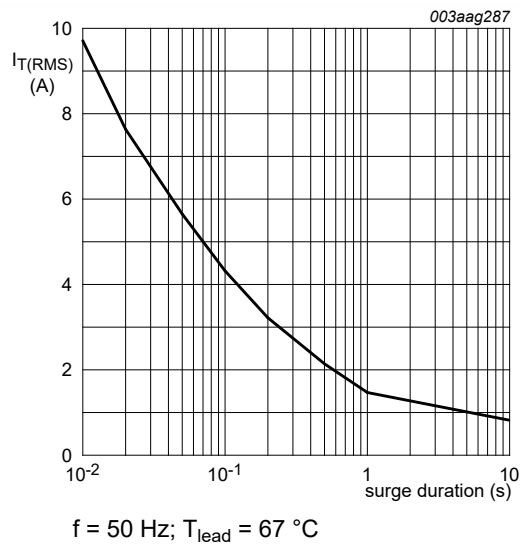


Fig. 3. RMS on-state current as a function of surge duration; maximum values

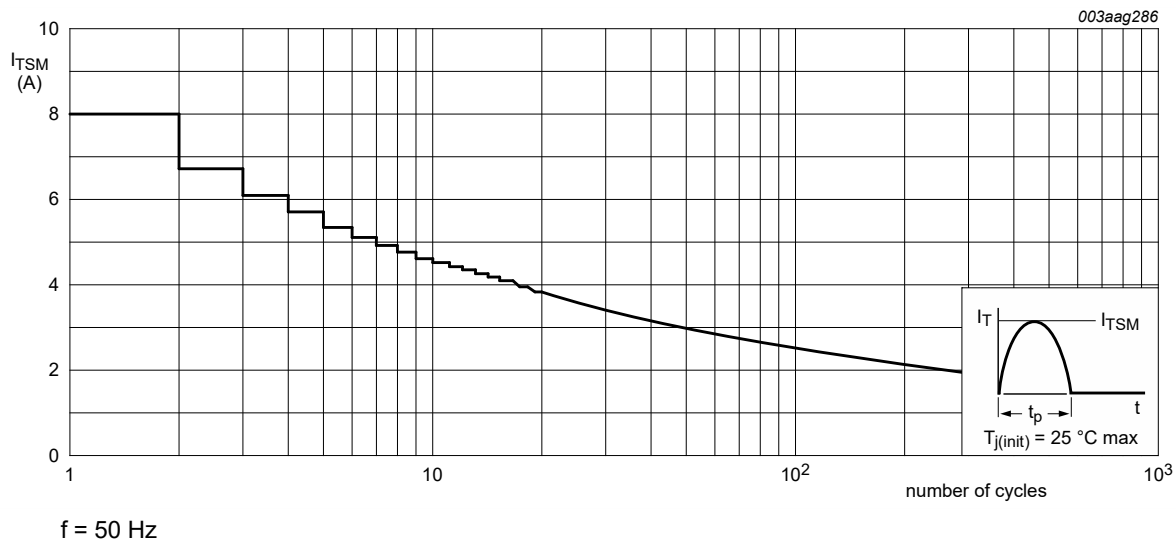
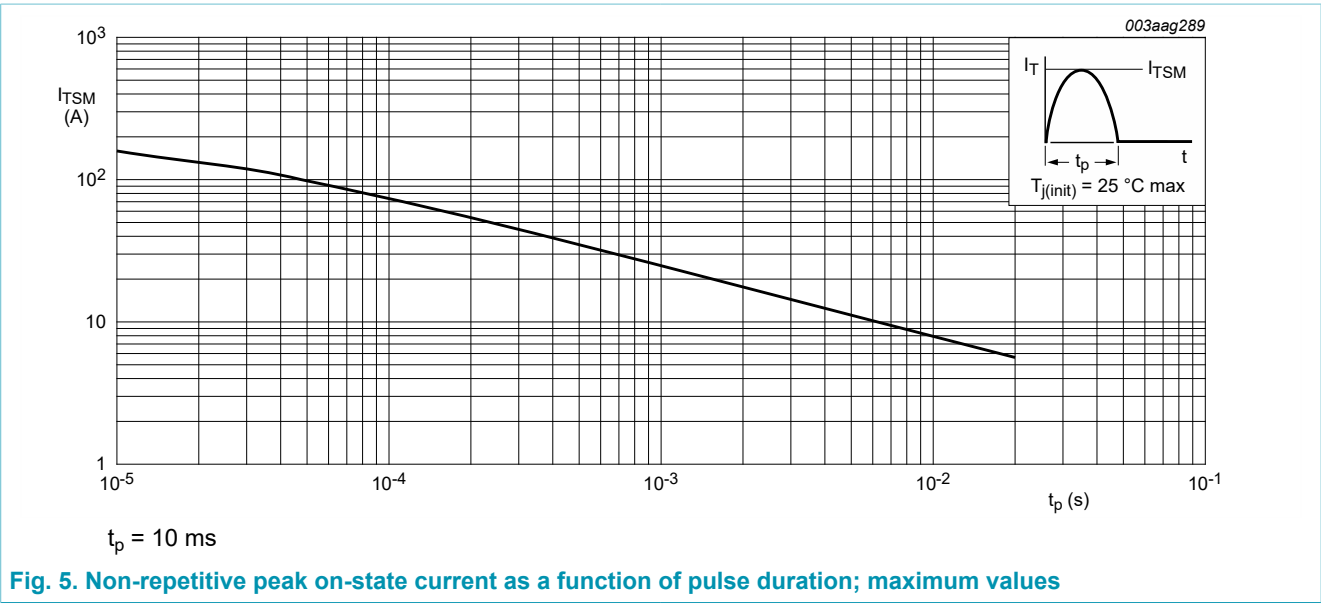


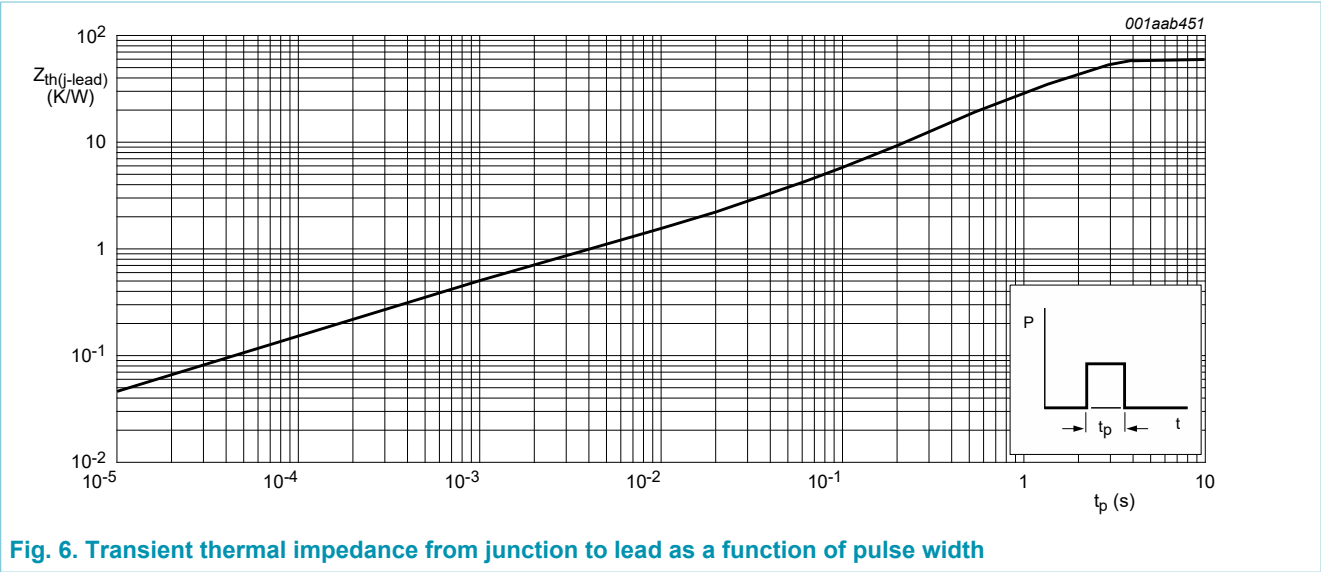
Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



8. Thermal characteristics

Table 5. Thermal characteristics

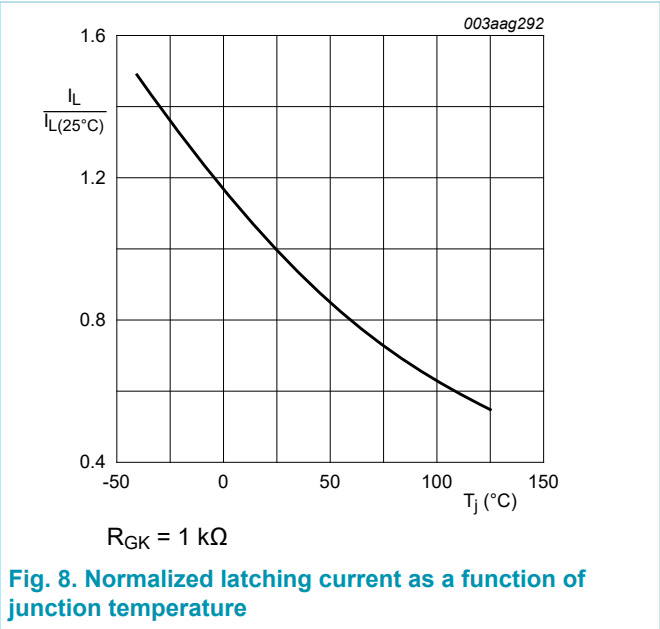
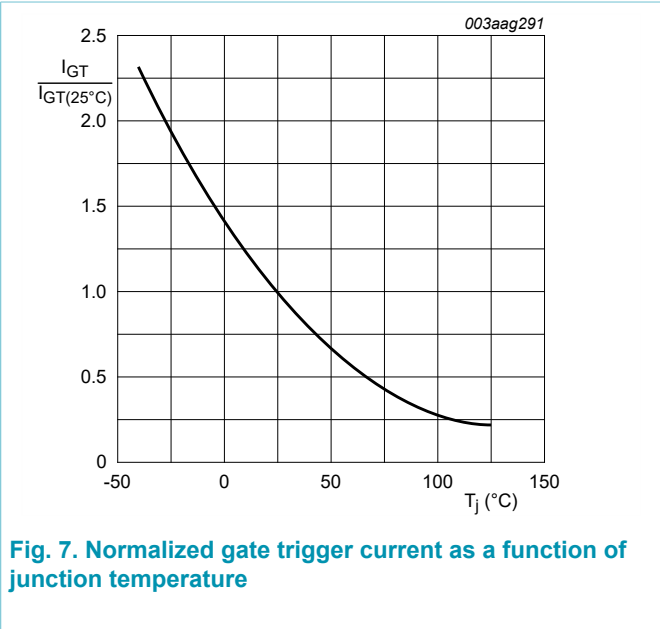
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead	<a href="#">Fig. 6</a>	-	-	60	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	printed circuit board mounted: lead length = 4 mm	-	150	-	K/W



9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 10 mA; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		0.5	-	7	μA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	-	6	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 9</a> ; <a href="#">Fig. 10</a>		-	-	5	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 1.6 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 11</a>		-	1.4	1.95	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 12</a>		-	-	0.8	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 400 V; T <sub>j</sub> = 25 °C		-	-	10	μA
		V <sub>D</sub> = 600 V; R <sub>GK(ext)</sub> = 1 kΩ; T <sub>j</sub> = 125 °C		-	-	100	μA
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C; R <sub>GK(ext)</sub> = 1 kΩ		-	-	10	μA
		V <sub>R</sub> = 600 V; T <sub>j</sub> = 125 °C; R <sub>GK(ext)</sub> = 1 kΩ		-	-	100	μA
Dynamic characteristics							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 402 V; T <sub>j</sub> = 125 °C; R <sub>GK</sub> = 1 kΩ; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; <a href="#">Fig. 13</a> ; <a href="#">Fig. 14</a>		75	-	-	V/μs



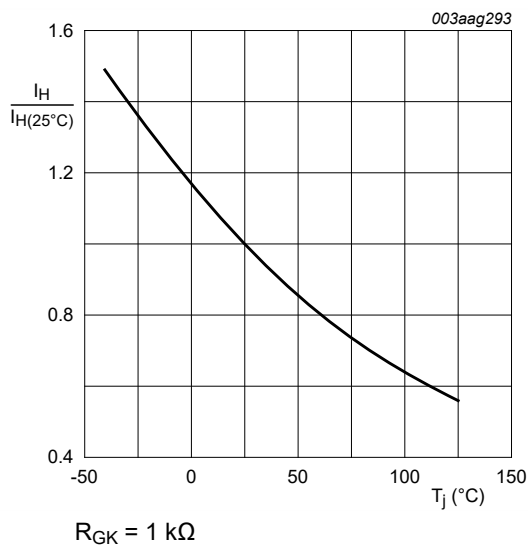


Fig. 9. Normalized holding current as a function of junction temperature

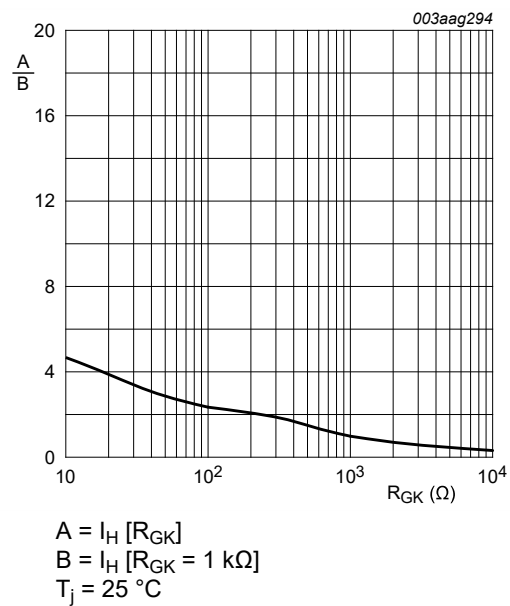


Fig. 10. Normalized holding current as a function of gate-cathode resistance (typical values)

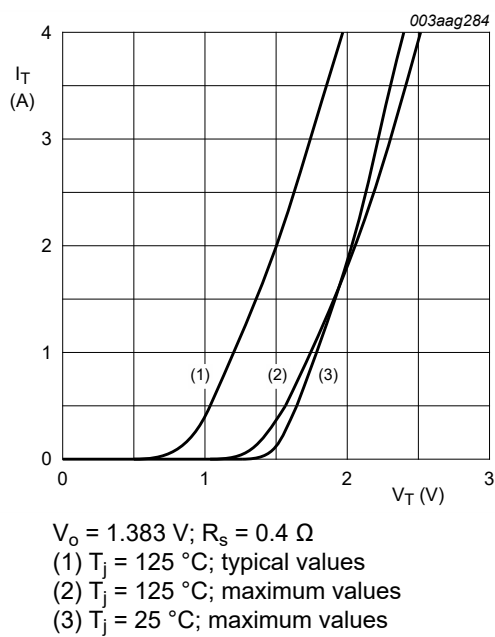


Fig. 11. On-state current as a function of on-state voltage

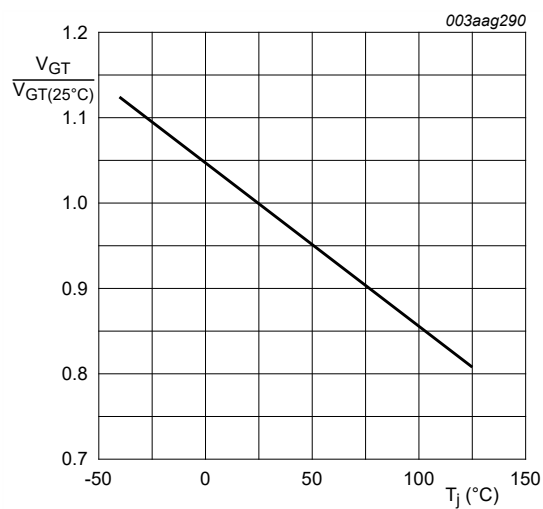
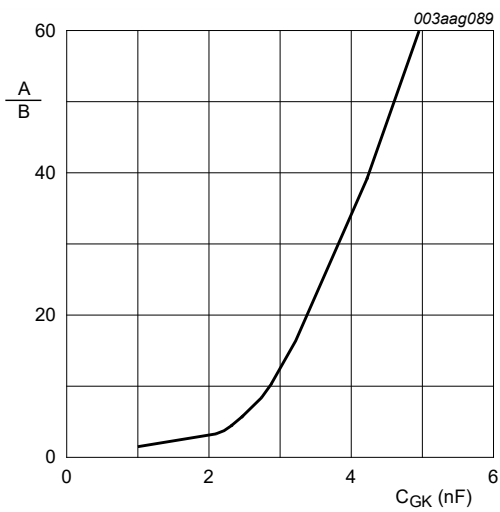
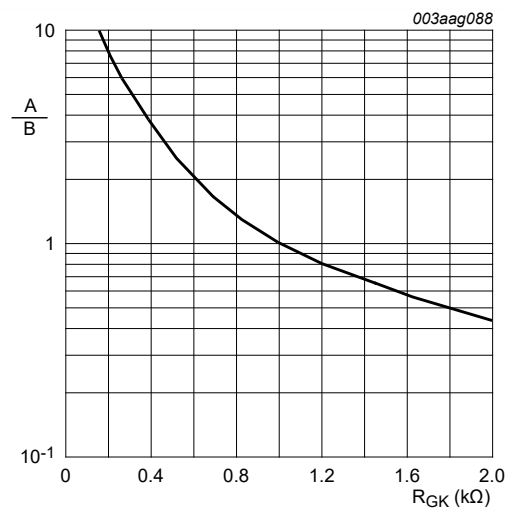


Fig. 12. Normalized gate trigger voltage as a function of junction temperature



$A = dV / dt [C_{GK}]$   
 $B = dV / dt [R_{GK} = 1\text{ k}\Omega]$   
 $T_j = 125\text{ }^\circ\text{C};$   
 $R_{GK} = 1\text{ k}\Omega; V_{DM} = 402\text{ V}$

Fig. 13. Normalized dVd/dt immunity as a function of gate-cathode capacitance (typical values)



$A = dV / dt [C_{GK}]$   
 $B = dV / dt [R_{GK} = 1\text{ k}\Omega]$   
 $T_j = 125\text{ }^\circ\text{C};$   
 $R_{GK} = 1\text{ k}\Omega; V_{DM} = 402\text{ V}$

Fig. 14. Normalized dVd/dt immunity as a function of gate-cathode resistance (typical values)

10. Package outline

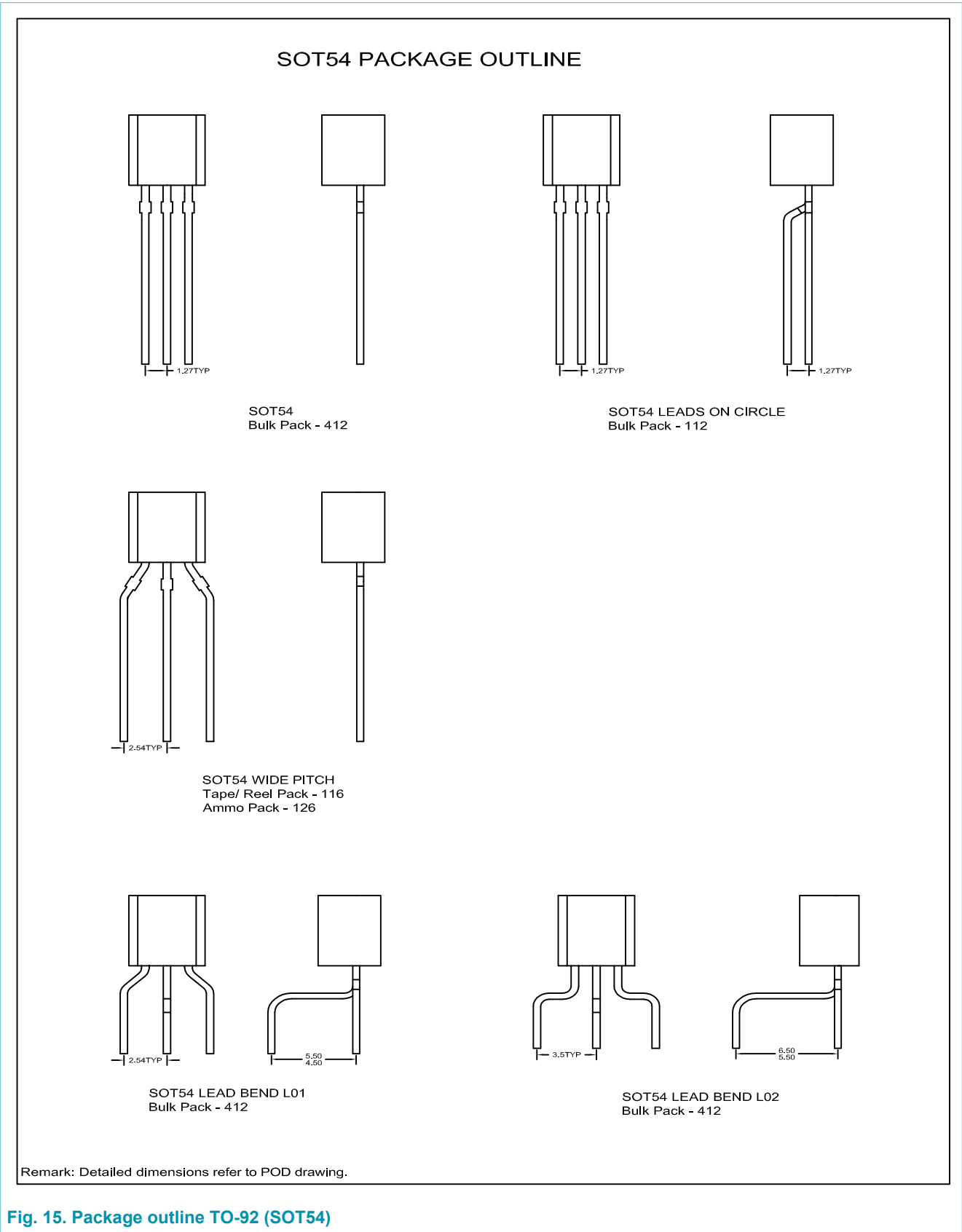


Fig. 15. Package outline TO-92 (SOT54)

## 11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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